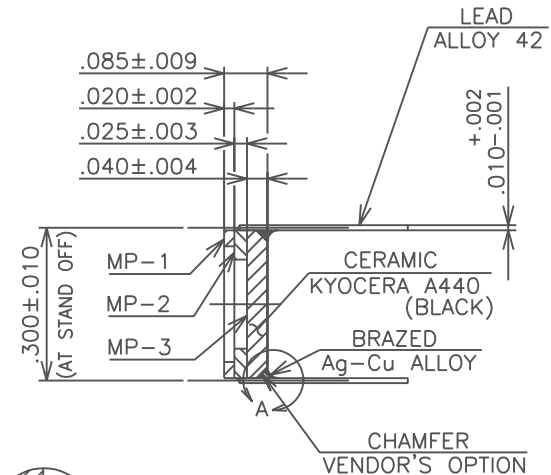
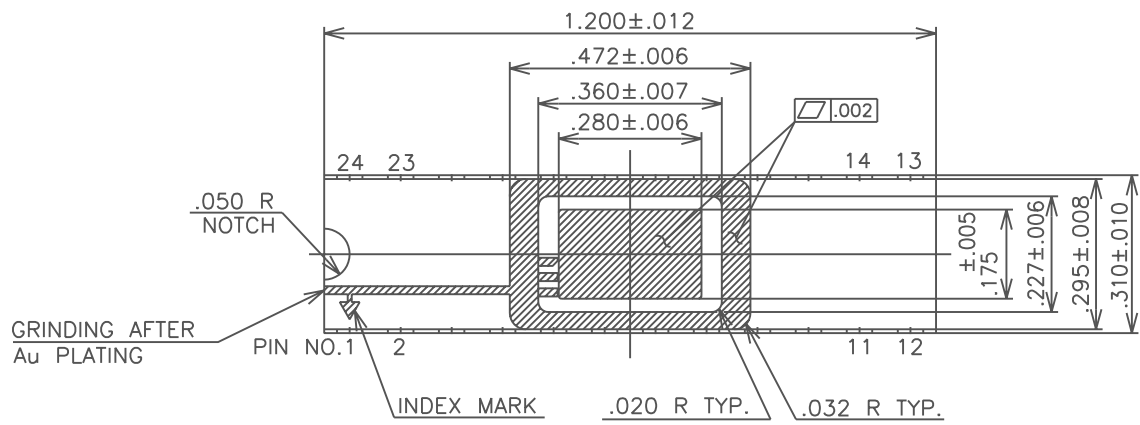
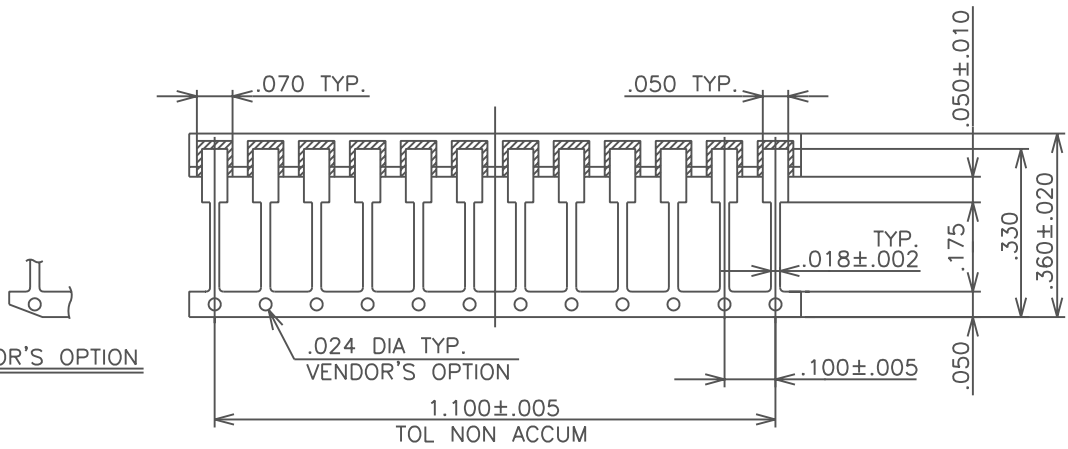


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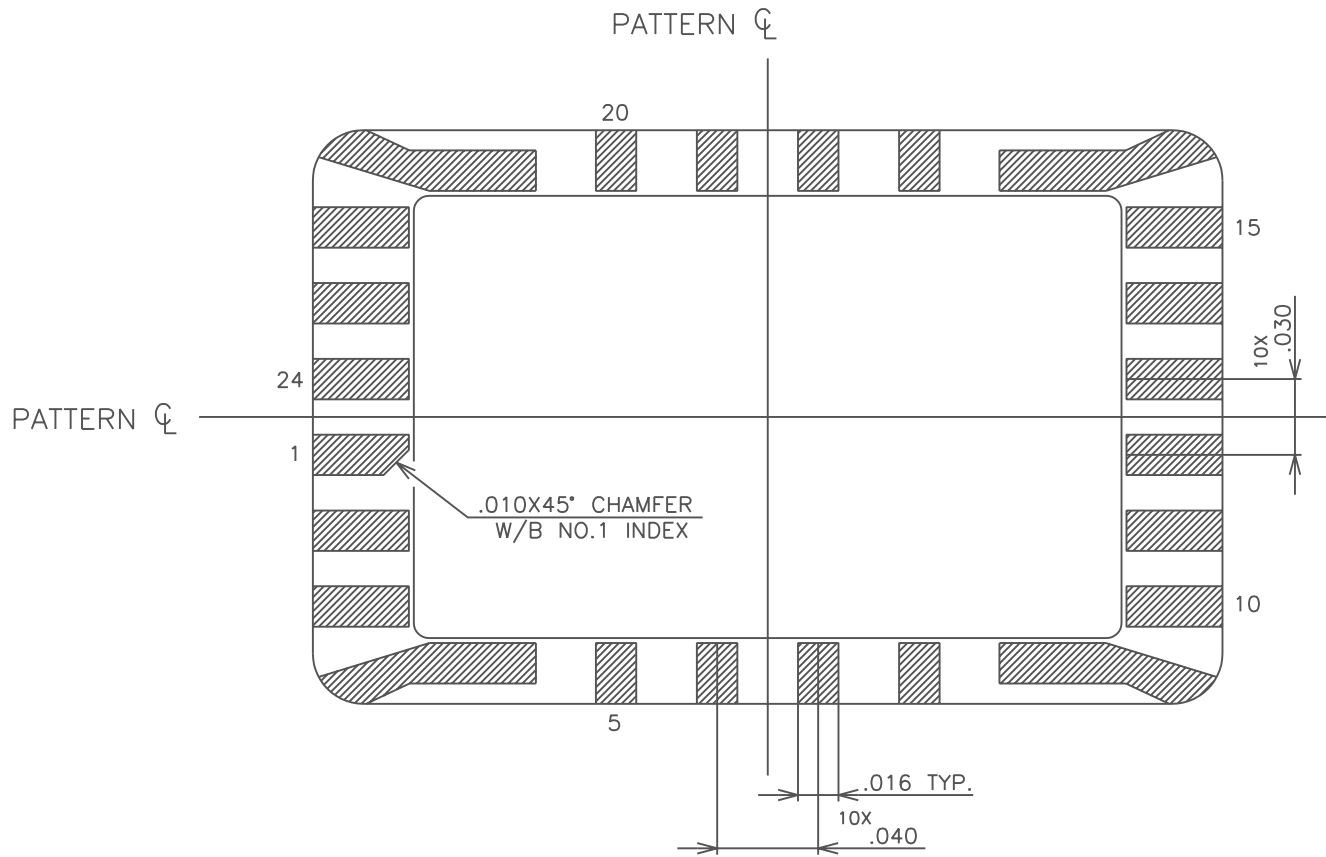


- NOTES**
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.3 OHM MAX.



| | | | | | | | | | | |
|--------------|--|--|--|------|-----------------------------|---------------------------------|------------|-----------|----------|------------|
| MODIFICATION | | | | | NAME | TOLERANCE | S=0 D=0 | | | |
| | | | | | 24 LEAD SIDE BRAZED PACKAGE | UNLESS OTHERWISE SPECIFIED | DRAWN | CHECKED | APPROVED | DATE |
| | | | | | SCALE 4 / 1 | MATERIAL AS INDICATED | T.S/H.K | H.TA/S.NI | H.SA | JAN.13.'01 |
| | | | | | | ±.005 THIRD ANGLE PROJECTION | | | | |
| CHANGED | | | | DATE | DRAWN | CHECKED | APPROVED | SSM P/N | | SHEET |
| | | | | | | | | CSB02477 | | 1 / 5 |





BONDING PATTERN

| | | | | | | | | | | | |
|--------------|---------|------|-------|---------|----------|-------------------------------------|---|---------------------|----------------------|------------------|--------------------|
| MODIFICATION | | | | | | NAME 24 LEAD SIDE BRAZED PACKAGE | TOLERANCE UNLESS OTHERWISE SPECIFIED | DRAWN T.S/H.K | CHECKED H.TA/S.NI | APPROVED H.SA | DATE JAN.13.'01 |
| | | | | | | SCALE 20 / 1 | MATERIAL | | | | |
| | | | | | | | THIRD ANGLE PROJECTION | | | | |
| | CHANGED | DATE | DRAWN | CHECKED | APPROVED | KYOCERA | KYOCERA CORPORATION KYOTO JAPAN | SSM P/N CSB02477 | SHEET 2 / 5 | | |

